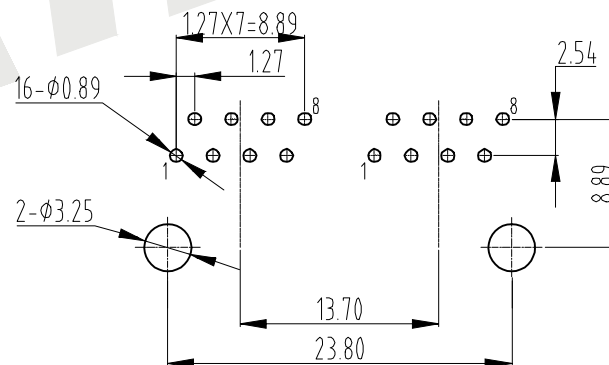
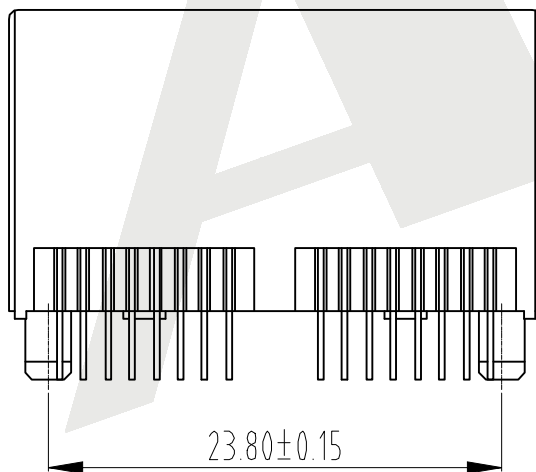
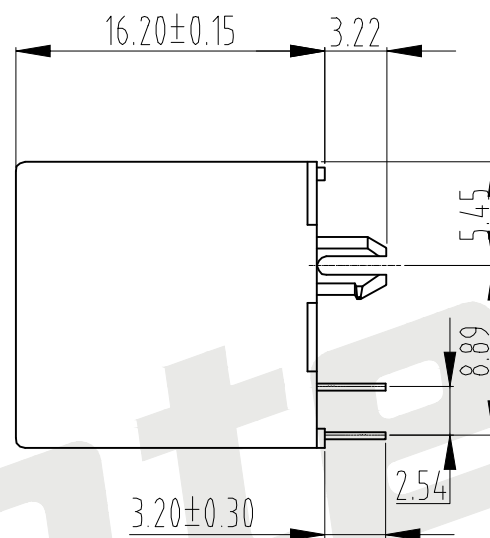
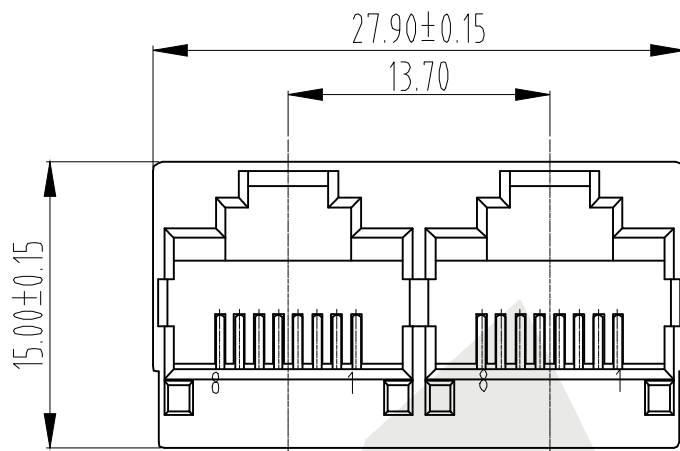


HSF



ROHS



PCB LAYOUT/TOP VIEW

NOTES:

MATERIAL:

- 1. HOUSING MATERIAL :GLASS FILLED POYESTER UL94V-0.
- 2. CONTACT MATERIAL :PHOSPHOR BRONZE t=0.3mm
- 3. PLATING :SELECTING GOLD PLATING 1μ~50μ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA

- 4. SHIELD :0.2mm THICKNESS COPPER WITH NICKEL PLATE

- ELECTRICAL
- 1. VOLTAGE RATING :125VAC RMS
 - 2. CURRENT RATING :1.5AMP
 - 3. CONTACT RESISTANCE:30 MILLIOHMS MAX
 - 4. INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
 - 5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

- MECHANICAL
- 1. DURRABILITY :750 CYCLES MIN
 - 2. PCB RETENTTON PRB-SOLDER :1 LB MIN

- REVRONMENTAL
- 1. STORAGE : -40° C TO 85° C
 - 2. OPERATION : 0° C TO 70° C

Order code:

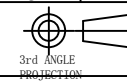
ATRJ5222 - 8P - 8C - X - A - B

- ①
- ②
- ③
- ④
- ⑤
- ⑥

- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact Plating
G0:Gold flash
G1: 3U" Gold
G2: 5U" Gold
G3:10U" Gold
G4:15U" Gold
G5:30U" Gold
SN:Tin
- ⑤ Shield
A:W/O Shield
B:Half Shield
C:Shield W/Eml
D:Shield W/O Eml
- ⑥ Ports
A:1X1P
B:1X2P
C:1X4P
D:1X5P
E:1X6P
F:1X8P

Unless Otherwise specified tolerance
 X. ±0.35 X.XX:±0.20
 X.X:±0.25 X.XXX:±0.15

SCALE: As Shown UNIT: mm
 DRAW Wu Fong Rong DATE 25/07/2019
 CHECK BobYang DATE 25/07/2019



Antenk® ANTENK ELECTRONICS CO., LTD
 Http://www.antenk.com
 E-mail:sales@antenk.com

TITLE: Modular Jack Top entry,
8P8C, 1X2Port Full Plastic

DRAWING NO: ATRJ5222-8P8C-X-A-B

PRODUCT NO: ATRJ5222-8P8C-X-A-B

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		